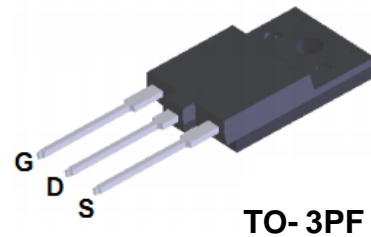
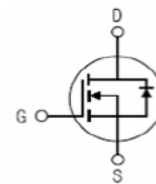


Features

- 3A, 1500V, $R_{DS(on)typ.} = 5\Omega @ V_{GS} = 10V, I_D = 1.5A$
- Low gate charge (typical 37nC)
- Low reverse transfer capacitance (typical 2.8pF)
- Fast switching
- 100% avalanche tested


TO- 3PF
Inner Equivalent Principium Chart

Absolute Maximum Ratings $T_c = 25\text{ }^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	STFW3N150F	Units
V_{DSS}	Drain – Source Voltage	1500	V
I_D	Drain Current	Continuous ($T_c = 25\text{ }^\circ\text{C}$)	3
		Continuous ($T_c = 100\text{ }^\circ\text{C}$)	1.8
I_{DM}	Drain Current - Pulsed (Note 1)	12	A
V_{GSS}	Gate – Source Voltage	± 30	V
EAS	Single Pulsed Avalanche Energy (Note 2)	225	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	5	V/ns
P_D	Power Dissipation ($T_c = 25\text{ }^\circ\text{C}$)	32	W
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to +150	$^\circ\text{C}$
T_L	Maximum lead temperature for soldering purposes 1/8" from case for 5 seconds	300	$^\circ\text{C}$

*Drain current limited by maximum junction temperature.

Thermal characteristics

Symbol	Parameter	STFW3N150F	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	3.8	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	40	$^\circ\text{C}/\text{W}$

Electrical Characteristics $T_c = 25\text{ }^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{DSS}	Drain – Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$	1500	--	--	V
$\Delta BV_{DSS}/\Delta T_j$	Breakdown Voltage Temperature Coefficient	$I_D = 250\text{ }\mu\text{A}$, Referenced to $25\text{ }^\circ\text{C}$	--	1.5	--	V/ $^\circ\text{C}$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 1500\text{ V}, V_{GS} = 0\text{ V}$	--	--	25	μA
		$V_{DS} = 1200\text{ V}, T_c = 125\text{ }^\circ\text{C}$	--	--	500	μA
I_{GSSF}	Gate-Body Leakage Current, Forward	$V_{GS} = 30\text{ V}, V_{DS} = 0\text{ V}$	--	--	100	nA
I_{GSSR}	Gate-Body Leakage Current, Reverse	$V_{GS} = -30\text{ V}, V_{DS} = 0\text{ V}$	--	--	-100	nA
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage (Note 4)	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$	3.0	--	5.0	V
$R_{DS(on)}$	Static Drain-Source on-Resistance (Note 4)	$V_{GS} = 10\text{ V}, I_D = 1.5\text{ A}$	--	5	8	Ω
g_{FS}	Forward Transconductance (Note 4)	$V_{DS} = 30\text{ V}, I_D = 1.5\text{ A}$	--	4.5	--	S
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS} = 25\text{ V}, V_{GS} = 0\text{ V}, f = 1.0\text{ MHz}$	--	1938	--	pF
C_{oss}	Output Capacitance		--	104	--	pF
C_{rss}	Reverse Transfer Capacitance		--	2.8	--	pF
R_g	Gate resistance	$F = 1.0\text{ MHz}$	--	4.0	--	Ω
Switching Characteristics						
$t_{d(on)}$	Turn-On Delay Time	$V_{DS} = 750\text{ V}, I_D = 3.0\text{ A}, R_G = 10\text{ }\Omega, V_{GS} = 10\text{ V}$ (Note 4,5)	--	35	--	ns
t_r	Turn-On Rise Time		--	19	--	ns
$t_{d(off)}$	Turn-Off Delay Time		--	56	--	ns
t_f	Turn-Off Fall Time		--	30	--	ns
Q_g	Total Gate Charge	$V_{DS} = 750\text{ V}, I_D = 3.0\text{ A}, V_{GS} = 10\text{ V}$ (Note 4,5)	--	37	--	nC
Q_{gs}	Gate-Source Charge		--	10	--	nC
Q_{gd}	Gate-Drain Charge		--	14	--	nC
Drain – Source Diode Characteristics and Maximum Ratings						
I_S	Maximum Continuous Drain-Source Diode Forward Current		--	--	3	A
I_{SM}	Maximum Pulsed Drain-Source Diode Forward Current		--	--	12	A
V_{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0\text{ V}, I_S = 3.0\text{ A}$	--	--	1.5	V
t_{rr}	Reverse Recovery Time	$V_{GS} = 0\text{ V}, I_S = 3.0\text{ A}$	--	880	--	ns
Q_{rr}	Reverse Recovery Charge	$di_f/dt = 100\text{ A}/\mu\text{s}$ (Note 4)	--	6.5	--	μC

Notes:

1. Repetitive Rating : Pulsed width limited by maximum junction temperature
2. $L = 10.0\text{ mH}$, $I_{AS} = 6.7\text{ A}$, $R_G = 25\text{ }\Omega$, Starting $T_j = 25\text{ }^\circ\text{C}$
3. $I_{SD} \leq 3.0\text{ A}$, $di/dt \leq 100\text{ A}/\mu\text{s}$, $V_{DD} \leq BV_{DSS}$, Starting $T_j = 25\text{ }^\circ\text{C}$
4. Pulsed Test : Pulsed width $\leq 300\text{ }\mu\text{s}$, Duty cycle $\leq 2\%$
5. Essentially independent of operating temperature

Characteristics Curve

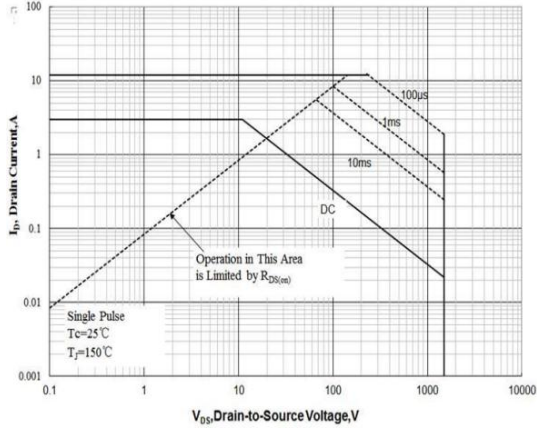


Figure 1 Maximum Forward Bias Safe Operating Area

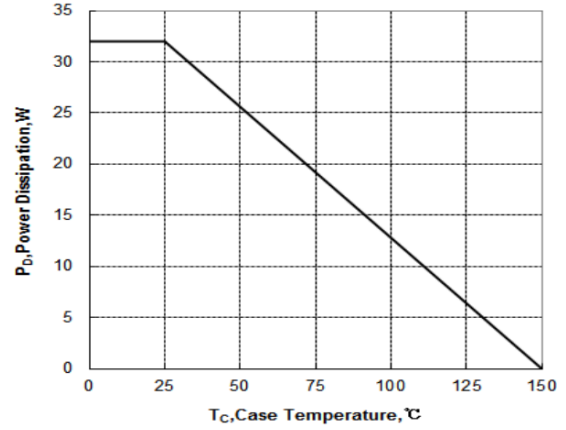


Figure 2 Maximum Power dissipation vs Case Temperature

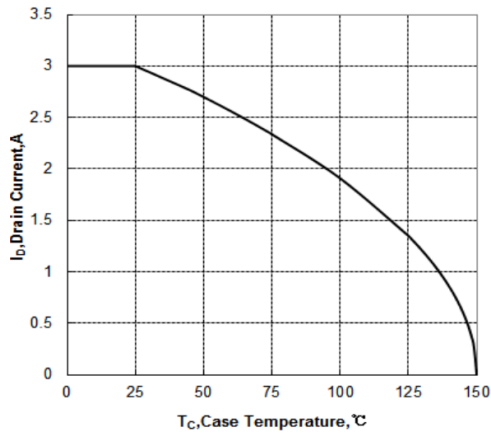


Figure 3 Maximum Continuous Drain Current vs Case Temperature

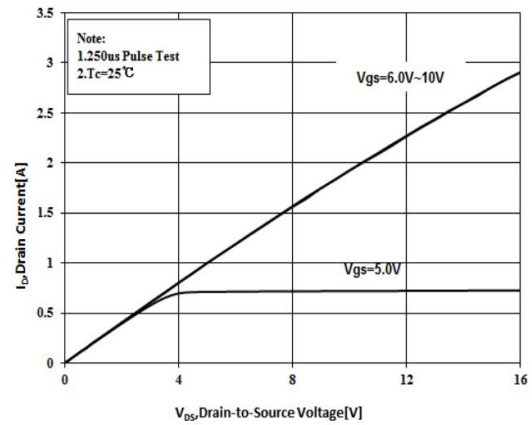


Figure 4 Typical Output Characteristics

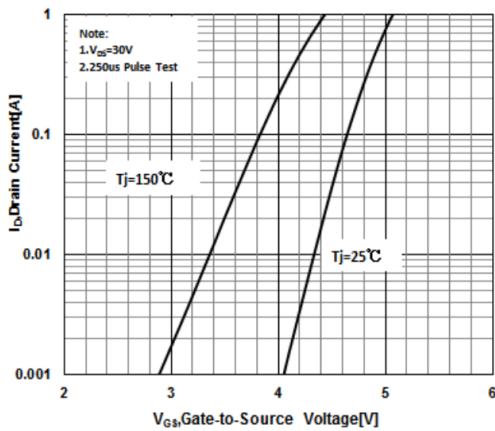


Figure 5 Typical Transfer Characteristics

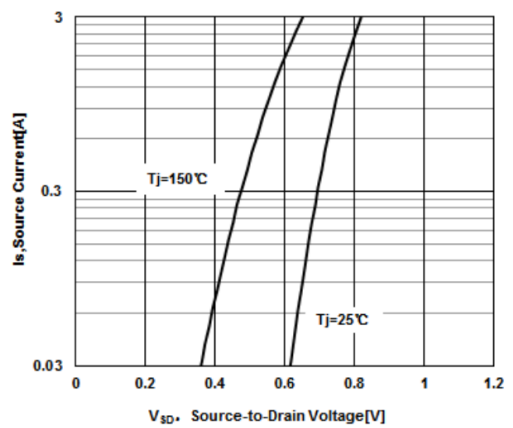


Figure 6 Typical Body Diode Transfer Characteristics

Characteristics Curve

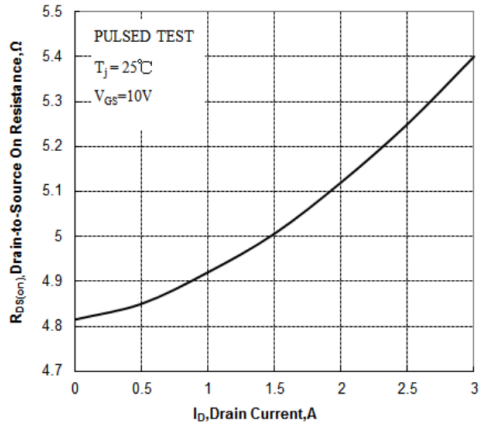


Figure 7 Typical Drain to Source ON Resistance vs Drain Current

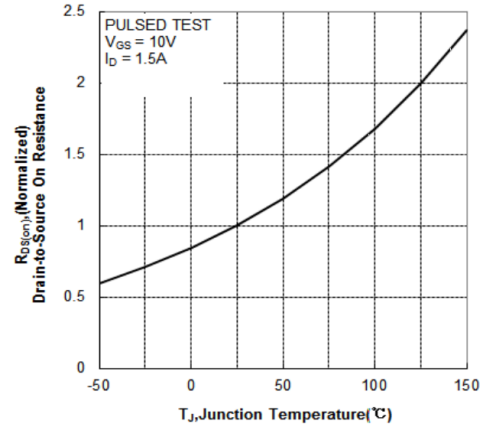


Figure 8 Typical Drain to Source on Resistance vs Junction Temperature

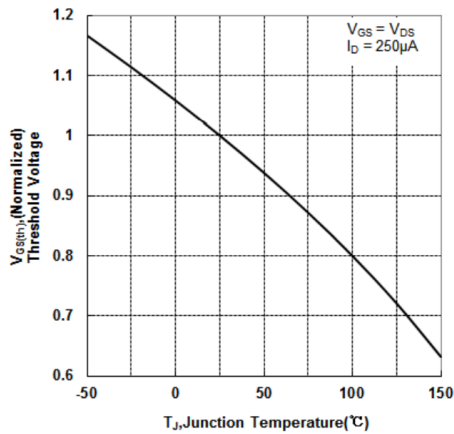


Figure 9 Typical Threshold Voltage vs Junction Temperature

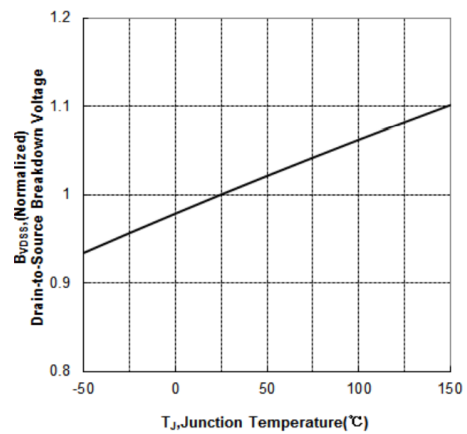


Figure 10 Typical Breakdown Voltage vs Junction Temperature

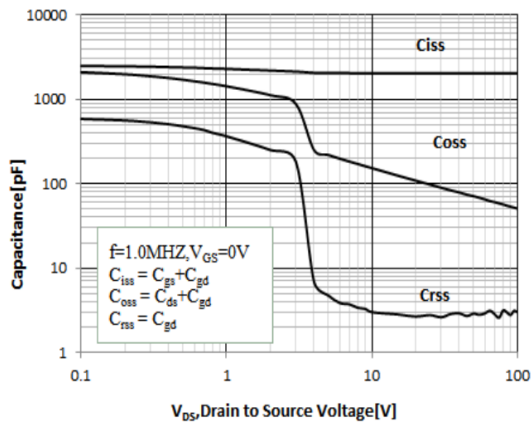


Figure 11 Typical Capacitance vs Drain to Source Voltage

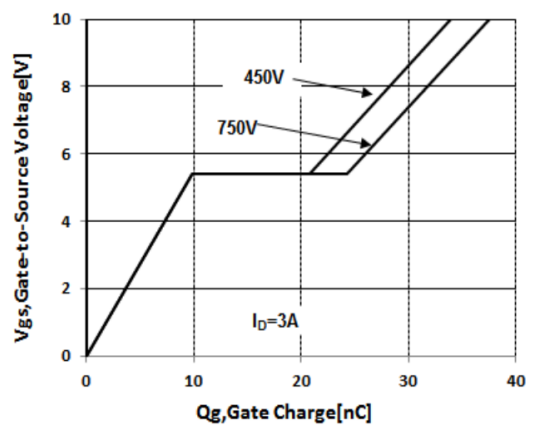


Figure 12 Typical Gate Charge vs Gate to Source Voltage

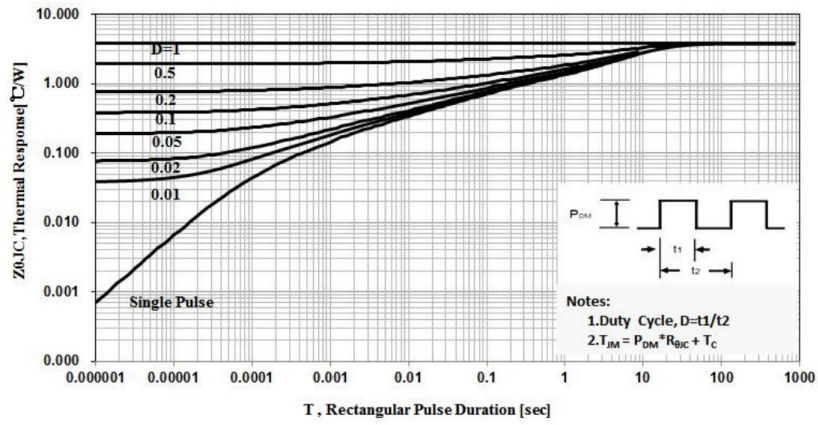
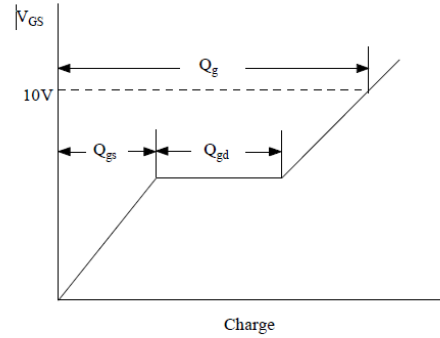
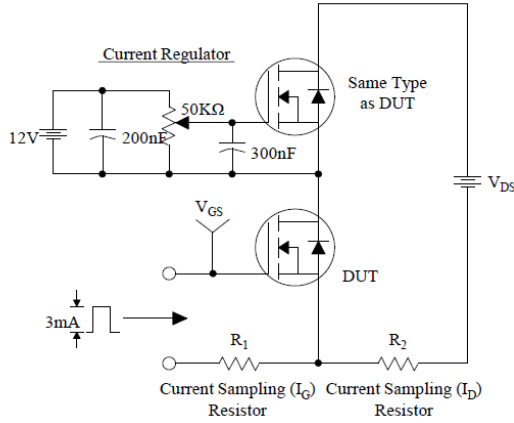
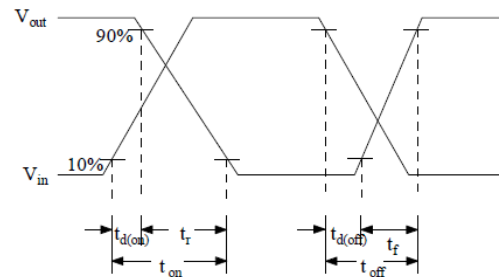
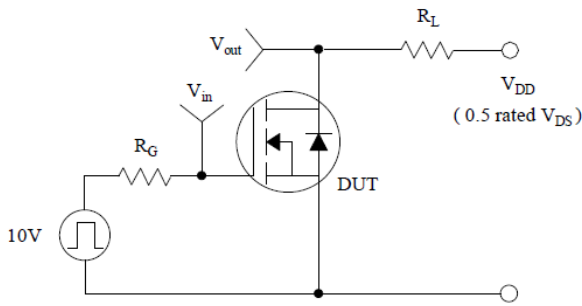


Figure 13 Maximum Effective Thermal Impedance , Junction to Case

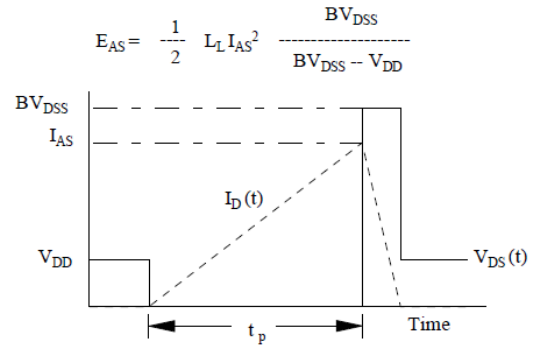
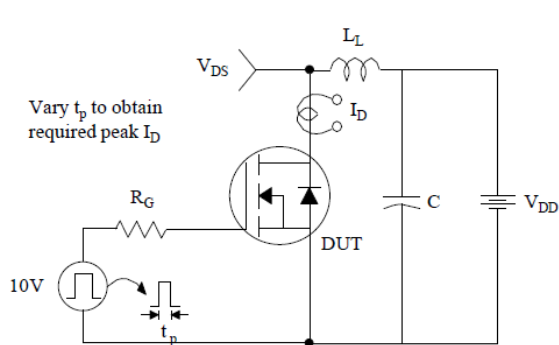
Test Circuit & Waveform



Gate Charge Test Circuit & Waveform

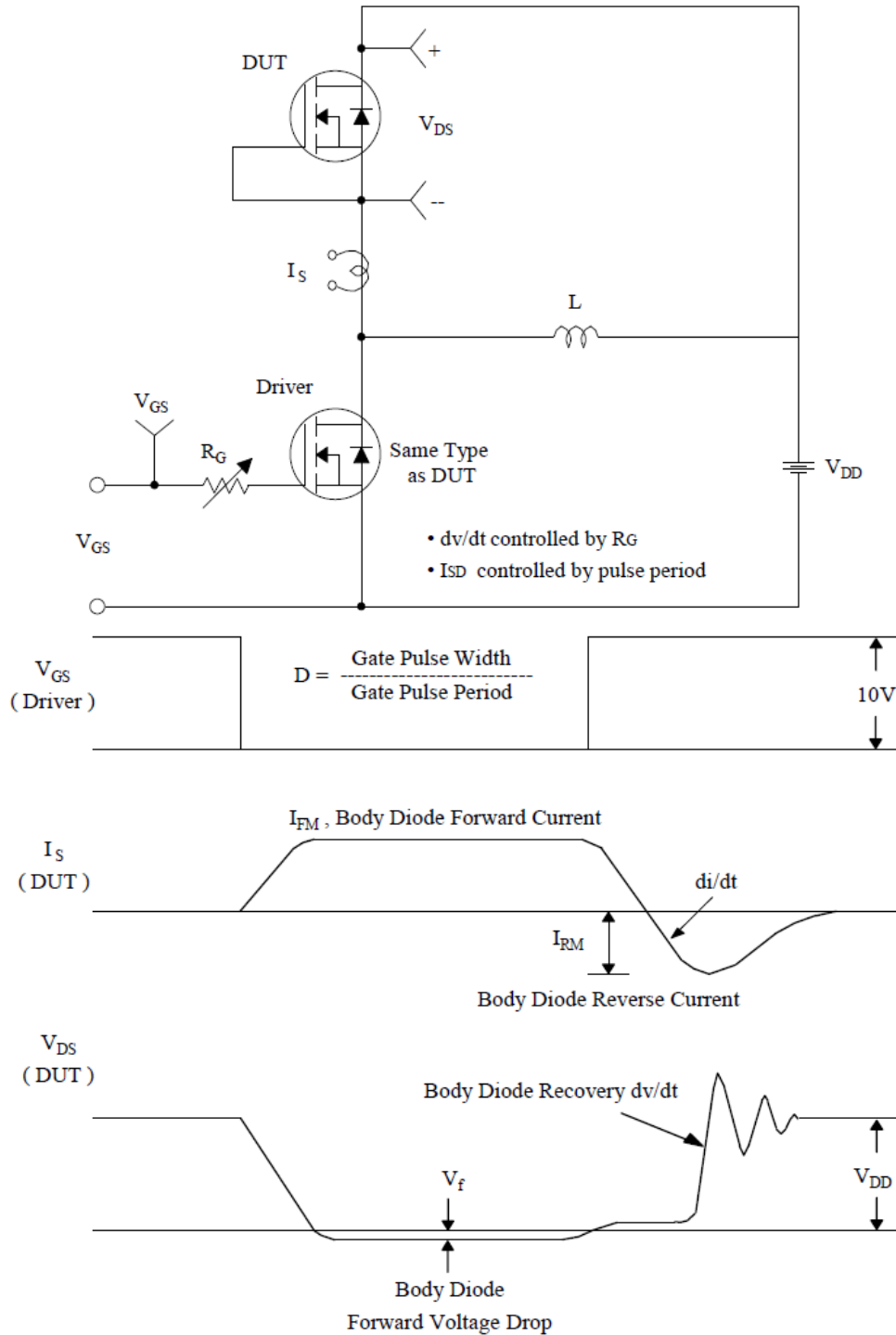


Resistive Switching Test Circuit & Waveforms



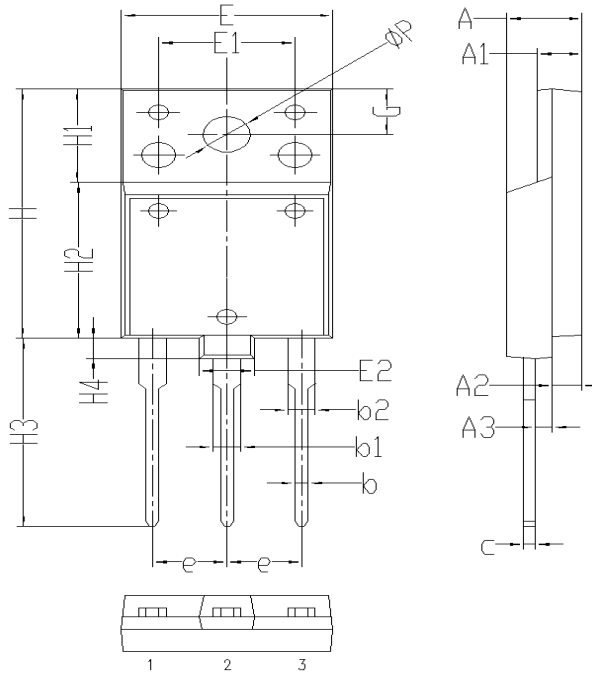
Unclamped Inductive Switching Test Circuit & Waveforms

Test Circuit & Waveform



Peak Diode Recovery dv/dt Test Circuit & Waveforms

Package Information



Symbol	单位 mm		
	Min	Nom	Max
A	5.35	5.55	5.75
A1	2.80	3.00	3.20
A2	1.90	2.10	2.30
A3	1.10	1.30	1.50
b	0.65	0.75	0.85
b1	1.80	2.00	2.20
b2	1.80	2.00	2.20
c	0.70	0.90	1.10
e	5.25	5.45	5.65
E	15.3	15.5	15.7
E1	9.80	10.0	10.2
E2	3.80	4.00	4.20
H	24.3	24.5	24.7
H1	9.00	9.20	9.40
H2	15.1	15.3	15.5
H3	18.5	19.0	19.5
H4	1.80	2.00	2.20
H5	4.80	5.00	5.20
G	4.3	4.5	4.7
ΦP	3.40	3.60	3.80